SURFACE MOUNT SILICON TRIPLE ISOLATED SCHOTTKY DIODE



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMKSH-3T contains three (3) isolated silicon Schottky diodes, epoxy molded in an SOT-363 surface mount package. This device has been designed for switching applications requiring a low forward voltage drop.

MARKING CODE: KHT



SOT-363 CASE

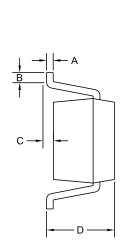
MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Continuous Forward Current	ΙF	100	mA
Peak Repetitive Forward Current	I _{FRM}	350	mA
Peak Forward Surge Current, tp=10ms	I _{FSM}	750	mA
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

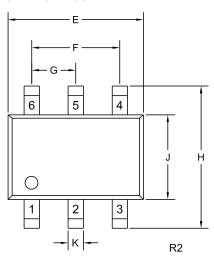
ELECTRICAL CHARACTERISTICS PER DIODE: (T _A =25°C unless otherwise noted)								
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS			
^I R	V _R =25V		90	500	nA			
I_R	V _R =25V, T _A =100°C		25	100	μΑ			
BV_R	I _R =100μA	30			V			
VF	I _F =2.0mA		0.29	0.33	V			
V_{F}	I _F =15mA		0.37	0.45	V			
V_{F}	I _F =100mA		0.51	1.00	V			
CJ	V _R =1.0V, f=1.0MHz		7.0		pF			
t _{rr}	$I_F = I_R = 10$ mA, $I_{rr} = 1.0$ mA, $R_L = 100$ Ω			5.0	ns			

SURFACE MOUNT SILICON TRIPLE ISOLATED **SCHOTTKY DIODE**

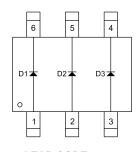


SOT-363 CASE - MECHANICAL OUTLINE





PIN CONFIGURATION



DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.004	0.010	0.10	0.25			
В	0.005	-	0.12	-			
С	0.000	0.004	0.00	0.10			
D	0.031	0.043	0.80	1.10			
E	0.071	0.087	1.80	2.20			
F	0.051		1.30				
G	0.026		0.65				
Н	0.075	0.091	1.90	2.30			
J	0.043	0.055	1.10	1.40			
K	0.006	0.012	0.15	0.30			

LEAD CODE: 1) Anode D1

- 2) Anode D2
- 3) Anode D3 4) Cathode D3
- 5) Cathode D2
- 6) Cathode D1

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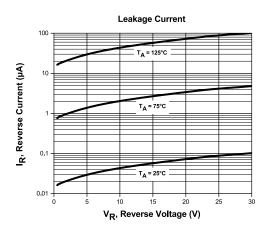
R5 (11-February 2016)

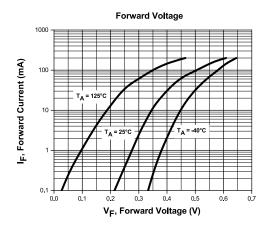
SOT-363 (REV: R2)

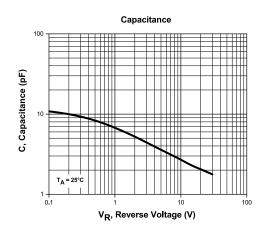
SURFACE MOUNT SILICON TRIPLE ISOLATED SCHOTTKY DIODE

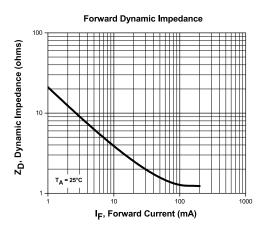


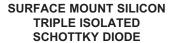
TYPICAL ELECTRICAL CHARACTERISTICS





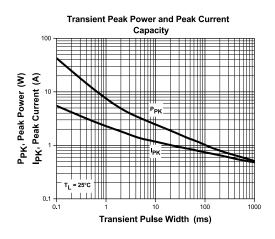


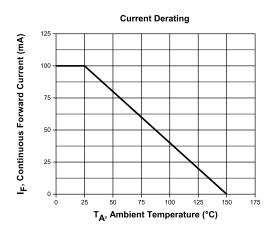


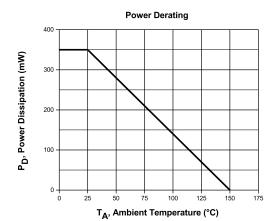




TYPICAL ELECTRICAL CHARACTERISTICS







OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- · Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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